

SPECIFICATION

- o Amend paragraph [0001] as follows:

[0001] This application is a divisional of co-pending Application No. 09/698,175, filed on October 30, 2000, and issued as U.S. Patent No. 6,675,450 on January 13, 2004, the entire contents of which are hereby incorporated by reference herein, and for which priority is claimed under 35 U.S.C. § 120.

- o Amend paragraph [0007] as follows:

[0007] Fig. 2 illustrates schematically this simple building block, commonly known as a T-Cell. Referring specifically to Fig. 2, a schematic of a T-Cell building block [[200]] 201 includes three TFR components 210, 220 and 230. TFR components 210 and 220 comprise the "series arm" portion of the T-Cell block, being connected in series between an input port [[215]] 214 and an output port 225 of T-Cell [[200]] 201. TFR component 230 comprises the "shunt leg" portion of T-Cell [[200]] 201, being connected in shunt between node 235 and ground. A TFR T-Cell itself may define a filter; although a TFR ladder filter typically has a plurality of these T-cells concatenated together.

- o Amend paragraph [0041] as follows:

[0041] Fig. 5(b) illustrates a device in which the supporting membrane is an integral part of the device. Note that, in the latter figure, no membrane film deposition (as described in step S2 of Fig. 3) would be required. Referring to Fig. 5(b), a membrane 222 spanning the un-etched remnants of the Si substrate 220 supports material on both its faces (top electrodes 205 and bottom electrode 215) and, as in the case of a TFR 200, communication between the top and bottom mounted electrodes is accomplished through the membrane 222. The membrane, in this case, is an integral part of the device and may be made of piezoelectric material such as AlN and SiN, for example, or any other known materials which have piezoelectric properties. The electrodes 205 and [[220]] 215 remain supportably attached to film 222 due to inherently strong bonding properties occurring between the layers, as is known to those skilled in the art. Wires or leads 223, which may be patterned as part of the device fabrication process, carry the electronic signal to and from the device, such as via top electrodes 205 as shown in Fig. 5(b).